

WHAT IS CLAIMED IS:

1. A manufacturing method for an organic EL element:
using a transfer member having at least a supporting member
and a light emitting layer formed peelably on the supporting
member and
a member to be transferred having at least a base member
and an electrode formed on the base member,
comprising a process of superimposing the light emitting
layer side of the transfer member and the electrode side of the
member to be transferred, and partially transferring at least
the light emitting layer from the transfer member onto the member
to be transferred,
wherein a bonding property improving substance is included
in at least one of the layer of the transfer member in contact
with the member to be transferred or the layer of the member
to be transferred in contact with the transfer member.
2. The manufacturing method for an organic EL element
according to claim 1, wherein the layer including the bonding
property improving substance is a hole transporting layer, an
electron transporting layer or a light emitting layer formed
at least in one of the transfer member or the member to be
transferred.
3. The manufacturing method for an organic EL element
according to claim 1, wherein an electron transporting layer
or a hole transporting layer is formed between the supporting

member and the light emitting layer.

4. A transfer member having at least a supporting member and a light emitting layer formed peelably on the supporting member, wherein a bonding property improving substance is included in the layer of the transfer member to be contacted with a member to be transferred.

5. The transfer member according to claim 4, wherein the layer including the bonding property improving substance is a hole transporting layer, an electron transporting layer or a light emitting layer.

6. A member to be transferred having at least a base member and an electrode formed on the base member, wherein a bonding property improving substance is included in the layer of the member to be transferred to be contacted with a transfer member.

7. The member to be transferred according to claim 6, wherein the layer including the bonding property improving substance is a hole transporting layer or an electron transporting layer.